# Part number SSSS811101 1.4 (H) mm, 1.5/2.0mm-travel Surface Mount Type SSSS8 Series

# Standard 😨

### **Basic information**

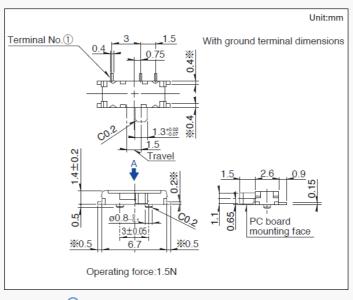


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Travel	1.5mm
Actuator directions	Horizontal
Actuator thickness	1.1mm
Poles	1
Positions	2
Operating force	Refer to the dimensions
Changeover timing	Not specified
Ground terminal	With
Soldering	Reflow
Dimensions (W×D×H)	6.7×2.6×1.4 mm

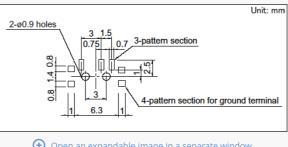
Operating tempe	rature range	-40°C to +85°C	
Rating (max.)/(mi	n.) (Resistive load)	0.3A 5V DC/50µA 3	V DC
Electrical performance	Contact resistance (Initial performance/After lifetime)	70mΩ max./130mΩ max. <b>r</b>	
	Insulation resistance	100MΩ min. 100V [	DC
	Voltage proof	100V AC for 1 minute	
/lechanical performance	Terminal strength	3N for 1 minute	
	Actuator strength	Operating direction	10N
		Pulling direction	10N
urability	Operating life without load	10,000 cycles 100m	ıΩ max.
	Operating life with load (at max. rated load)	10,000 cycles 130m	ιΩ max.
nvironmental	Cold	-40°C 500h	
erformance	Dry heat	85°C 500h	
	Damp heat	60°C, 90 to 95%RH	500h
linimum order	Japan	4,500	
unit(pcs.)	Export	18,000	

## Dimensions



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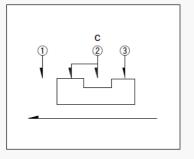
### Land Dimensions



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Viewed from direction A in the dimensions.

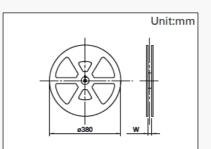
# **Circuit Diagram**



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# **Packing Specifications**

# Taping



(pcs.)			
4,500			
9,000			
18,000			
	9,000	9,000	9,000

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417×409×139

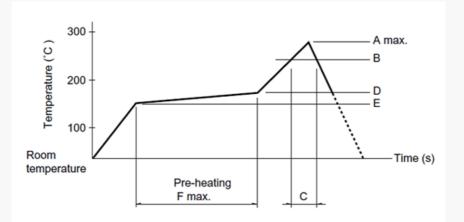
### **Soldering Conditions**

#### Example of Reflow Soldering Condition

- 1. Heating method Double heating method with infrared heater.
- 2. Temperature measurement

Thermocouple 0.1 to 0.2VCA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



A(°C) 3s max.	B(°C)	C(s)	D(°C)	E(°C)	F(s)
260	230	40	180	150	120

(1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, surface depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.

(2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

# **Reference for Hand Soldering**

Soldering temperature	
330±5°C	
Soldering time	

3s max.

# Notes are common to this series/models

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.

- 2. Please place purchase orders per minimum order unit (integer).
- 3. Products other than those listed in the above chart are also available. Please contact us for details.

## Cautions

- 1. Appling load to terminals during soldering under certain conditions may cause deformation and electrical property degradation.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the switches.

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3. Check and conform to soldering requirements under actual mass production conditions.

- 4. When soldering twice, wait until the first soldered portion cools to normal temperature. Continuous heating will deform the external portions, loosen or dislodge terminals, or may deteriorate their electrical characteristics.
- 5. Flux from around and above the PC board should not adhere to the switches.
- 6. After mounting the switches, if you intend to put the board into an oven in order to harden adhesive for other parts, please consult with us.
- 7. If you use a through-hole PC board or a PC board thinner or thicker than the recommendation, here may be greater heat stress. Verify the soldering conditions thoroughly before use.
- 8. Solder the switches with detent at the detent position. Soldering switches fixed at the center of the detent may deform the detent mechanisms.
- 9. No cleaning.
- 10. Protect small and thin switches from external forces in the set mounting process.
- 11. Tighten the mounting screws by applying the specified torque. Tightening with larger torque than the specified one will result in malfunction or breakage of screws.
- 12. Insert these switches to the specified mounting surface and mount them horizontally. If not mounted horizontally, these switches will malfunction.
- 13. The products are designed and manufactured for direct current resistance. Contact us for use of other resistances such as inductive (L) or capacitive (C).
- 14. The switch will be break if you apply a greater stress than that specified. Take great care not to let the switch be subject to greater stress than specified.
- 15. Use of the switches in a dusty environment may lead the dusts entering through the openings and cause imperfect contact or malfunction. Take this into account for set design.
- 16. Corrosive gas if generated by peripheral parts of a set, malfunction such as imperfect contact may occur. Thorough investigation shall be required beforehand.
- 17. Storage

Store the products as delivered at normal temperature and humidity, out of direct sunlight and away from corrosive gases. Use them as soon as possible and no later than six months after delivery.

Once the seal is broken, use them as soon as possible.

## **Measurement and Test Methods**

#### **Rotational Torque (Operating Force)**

Measures the torque (operating force) necessary to rotate (move) the shaft (lever). Unless otherwise specified, measurement shall be made at ambient temperatures of 5 to 35°C, the shaft rotational speed shall be 60° per second, and the lever traveling speed shall be 20mm per second.

#### Shaft Wobble

Measures the amount of deflection at the specified position from the reference plane, with the specifiedbending moment, applied perpendicularly to the shaft from directions 180 degrees with respect to each other.

#### Withstand Voltage

Applies AC voltage to the specified spot for a minute and then checks for arc, burning, dielectric breakdown and other abnormalities. Respective terminals may be tested as a group. The sections described below shall be tested unless otherwise specified. However, if the section concerned is so constructed as to conduct, that particular part shall not be tested.

#### **Insulation Resistance**

Applies specified voltage to the specified locations and then measures the insulation resistance with a megger. The locations described below shall be tested unless otherwise specified. However, if the section concerned is so constructed as to conduct, that particular part shall not be tested.

### Sections to be Tested for Withstand Voltage and Insulation Resistance

- Between terminal and shaft (lever).
- Between terminal and metal cover (frame).

#### Shaft (Lever) Strength against Push/Pull Actions

Applies a specified force in the axial direction of the shaft (lever) for 19 seconds and then checks the operating part and other sections for deformation, breakage, operating conditions, etc.